

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **06/12/2022**

Details for "TUSB7320RKM"R

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TUSB7320RKM	NIPDAU	Level-3-260C-168 HR	TI PHILIPPINES CLARK A/T	RKM 100	9x9x0.75	290.6

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.75235	99.997608	999976	0.258869	2589
Copper and Its Alloys	Iron	7439-89-6	0.00003	0.000399	4	0.000001	0
Nickel and Its Alloys	Nickel	7440-02-0	0.00001	0.000133	1	0	0
Other Inorganic Materials	Sulfur	7704-34-9	0.00001	0.000133	1	0	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.00002	0.000266	3	0.000001	0
Precious Metals	Silver	7440-22-4	0.000011	0.001462	15	0.000004	0
Sub-Total			0.752368	100	1000000	0.258875	2589
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	2.627625	81.100013	811000	0.904113	9041
Thermoplastics	Epoxy	85954-11-6	0.612356	18.899987	189000	0.210699	2107
Sub-Total			3.239981	100	1000000	1.114813	11148
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	189.748008	97.607	976070	65.288491	652885
Copper and Its Alloys	Iron	7439-89-6	4.2768	2.2	22000	1.471561	14716
Copper and Its Alloys	Phosphorus	7723-14-0	0.062208	0.032	320	0.021405	214
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.001944	0.001	10	0.000669	7
Zinc and Its Alloys	Zinc	7440-66-6	0.31104	0.16	1600	0.107023	1070
Sub-Total			194.4	100	1000000	66.889148	668891
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.99752	95.12	951200	0.687307	6873
Precious Metals	Gold	7440-57-5	0.01638	0.78	7800	0.005636	56
Precious Metals	Palladium	7440-05-3	0.0861	4.1	41000	0.029625	296
Sub-Total			2.1	100	1000000	0.722568	7226
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	75.245299	90.5	905000	25.890401	258904
Other Plastics and Rubber	Carbon Black	1333-86-4	0.41572	0.5	5000	0.143041	1430
Thermoplastics	Epoxy	85954-11-6	7.482958	9	90000	2.574736	25747
Sub-Total			83.143977	100	1000000	28.608178	286082
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	6.993776	100	1000000	2.406418	24064
Sub-Total			6.993776	100	1000000	2.406418	24064
Total			290.630102			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.